





IMT-MINAFAB: a Technological Platform for integrating Education, Research and Innovation

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•Summary

- About IMT-MINAFAB in brief.
- Main facts, main figures.
- Major fields of research.
- Current projects.
- Equipment overview.
- Collaboration and perspectives.



The policy of the National Institute for R&D in Microtechnologies (IMT-Bucharest) is to concentrate the operation of experimental resources in the so-called IMT-MINAFAB (IMT Centre for Micro-and NAnoFABrication).

This is done for technical reasons (the need to install and operate many equipments in a clean room environment) and also for organizational reasons – the need to have a concetration of resources open for utilization of both internal and external (non IMT) customers.

IMT operates a variety of resources, from CAD and a mask shop to reliability testing.

Of particular importance are the equipments for nanostructuring and characterization.

This allows IMT to participate in various international projects, including in nanoelectronics (such as CATHERINE from FP7 and a couple of projects from ENIAC-JU).



The experimental facility IMT-MINAFAB is not only devoted to partnership in research: the centre is also open to education and industry and this opens the way for very fruitful interactions in the so-called "knowledge triangle"

IMT will benefit from the interaction envisaged with companies like Infinineon Technologies or Honeywell (providing services and/or cooperating in research projects closer to the real needs of industry),

as well as from its involvment in educational and training activities (providing full support for a number of four disciplines related to the new M.Sc. courses from University "Politehnica" of Bucharest or rulling the new IMT post doctoral programme in microand nanotechnologies with 35 students).





- State of the art research infrastructure, operating since September 2008.
- Center of services for micro- and nanofabrication
- Platform of interaction as open-centre for research and education-by research, focused on multidisciplinary innovation and knowledge transfer to industry.
- Enables highly efficient exploitation of IMT's existing tangible and intangible assets in nano-science/technologies (clean-room facility, advanced equipments, knowledge and experience, partners and clients).
- **Complex technological platform**: CAD tools, mask shop sector, analysis and characterization, nano-bio-fabrication, reliability tests.
- Access is facilitated in a variety of ways, with notable accent on developing common R&D projects and on offering direct access of innovative companies



Main facts, main figures [1]

- Class 1000 clean room (220 sqm) for the mask shop and the most demanding technological processes.
- Class 100,000 clean room so called "Grey area" (200 sqm), mostly for the characterization equipments.
- **Class 10,000 clean room** (120 sqm) for thin films by CVD techniques, RTP, etc. (to become operational).

• Accumulated total investment in equipments and infrastructure: about 9 M Euro (2006-2009: 7 M Euro; 2008: 3.5 M, mainly from Capacities projects).

Large range of services. *Main categories*:

- micro/nanofabrication for devices and systems
- inspection, analysis and characterization of surfaces, films, crystals, nanostructures
- design, modeling and simulation
- complex RDI services from design, to reliability testing





Main facts, main figures [2]

• Over 60 national users as partners in consortia, or based on bilateral agreements: 30 companies, 15 research institutes, 15 universities.

• Over 30 industrial users, as partners in consortia or contracted service users: Austria(1), Finland(1), France(1), Germany(8), Greece(1), Hungary(2), Italy(3), Poland(1), Slovakia(2), Spain(1), Sweden(6), The Netherlands(3), etc.

• Over 30 partners in research - FP6-7, bilateral projects: Belgium(2), Finland(1), France(2), Germany(11), Greece(1), Hungary(1), Italy(2), Ireland(1), Israel(1), Poland(1), Spain(1), The Netherlands(3), UK(1), Singapore(1), etc.



Master courses and hands-on training for students of Polytechnic University of Bucharest

• Operation of IMT-MINAFAB conforms with best technical/technological/ management standards (e.g., degree of decontamination, safety of operation



Main facts, main figures [3]

Accumulated funding based on:

three projects for technological networks (2005-2008) - NanoScaleLab and NanoBioLab, labs created in this context: nuclei of some current experimental labs

► four infrastructure projects (2006-2008) - extension of capabilities

eight infrastructure projects from the "Capacities" programme (2007-2009) - five of them consolidated the "Centre of Nanotechnologies"; reconstruction/updating of the premises.

MIMOMEMS (FP7- REGPOT –call1) project : a Centre of Excellence in Microwave, Millimetre Wave and Optical Devices, based on Micro-Electro-Mechanical Systems for Advanced Communication Systems and Sensors, in funded by the EU project No. 202897

Various research projects in national programmes.



Main facts, main figures [4]

Results:

• IMT- MINAFAB as an integrated cluster of new experimental laboratories initiated and operated by various research groups. Other equipments that can be used for production (mask shop, wafer processing etc.) are managed by execution personnel, in a dedicated department.

• Provides the experimental support for a number of interdisciplinary groups, such as:

-Centre of Nanotechnology (CNT-IMT) under the aegis of Romanian Academy. -MIMOMEMS Centre of Excellence in RF and Opto MEMS(2008-2011) - LEA (Associated European Laboratory) "Smart MEMS", IMT-Bucharest in association with LAAS/CNRS, Toulouse (France) and IESL-FORTH, Heraklion (Greece)

• Infrastructure providing state of the art services in micronanotechnology and hands on education and training.





Major fields of R&D

• Collaborative multidisciplinary research, focusing on convergent micro-nanobio technologies, based on structuring and characterization at the nanoscale.

Components for nanoelectronics, photonics and microwaves

- new fabrication technologies in Si, as well as in wide bandgap semiconductors, dielectrics, polymers.



-new concepts and structures for optical MEMS and RF-MEMS.

Advanced nanomaterials and nanostructures for therapies, biosensing, energy and other industries

- functionalized nanoporous materials, nanocomposite particles, microarrays.
- nanocomposite and film assemblies for fuel cells and photovoltaics.
- SAM's, immobilization and combined studies of molecular interactions.
- microfluidic components and biochips for biosensing and monitoring.
- functional films and nanocomposites for: neurosensing, constructions.



Major fields of R&D

- New technologies for fabrication and characterization
- nanolithography, mask-free nano-connections, high aspect-ratio nanostructures.
- silicon nanoelectrodes, functional porous silicon, bio-active materials, field emission nanostructures.
- soft-lithography and replication.
- rapid prototyping: dip-pen nanolithography, laser micromachining, 3D and inkjet printing.
- -nanomechanical characterization of materials.

IMT-MINAFAB currently provides a complex technological platform for basic research, application-oriented R&D and even small-scale production.











Gray Area



IMT- Bucharest participated in FP6 EU Projects



IMT-Bucharest

participated in different types of EU projects:

IPs, STREPS, NoEs, RTN- Marie Curie Network, SSA, CA in ICT and NMP Priorities



Participation of IMT- Bucharest in EU FP7 (and related) projects





Participation of IMT- Bucharest in EU FP7 Projects

► European Centre of Excellence in Microwave, Millimetre Wave and Optical Devices, based on Micro-Electro-Mechanical Systems for Advanced Communication Systems and Sensors – MIMOMEMS, Contract no. 202897, REGPOT call 2007-1, 2008-2011. Coordinator: IMT-Bucharest. Contact: Dr. Alexandru Muller, (<u>alexandru.muller@imt.ro</u>).

► Enabling MEMS-MMIC technology for cost-effective multifunctional RF-system integration - MEMS-4-MMIC, Contract no. 204101, STREP, FP7-ICT-2007-2, 2008-2011. Coordinator: IMST GmbH, Germany. IMT role Partner; IMT Contact: Dr. Dan Neculoiu, (dan.neculoiu@imt.ro).

► Carbon nAnotube Technology for High-speed nExt-geneRation nano-InterconNEcts - CATHERINE, coord: Dr. Stephen Trueman, CONSORZIO SAPIENZA INNOVAZIONE, Italy. Contract no. 216215, STREP, ICT, 2008-2011. IMT role Partner; IMT Contact: Adrian Dinescu, email: (adrian.dinescu@imt.ro).

Participation of IMT- Bucharest in EU FP7 Projects

► Flexible Patterning of Complex Micro Structures using Adaptive Embossing Technology – FlexPAET, IP, NMP, 2008-2010. Coord: Dr.-Ing. Christian Wenzel, Fraunhofer Gesellschaft zur Förderung der angewandten Forschung e.V. Fraunhofer Institut für Produktionstechnolgie (IPT), Germany. IMT role Partner; IMT Contact: Dr. Dana Cristea (dana.cristea@imt.ro);

European scale infrastructure in NanoBiotechnology - EuroNanoBio, CSA, NMP, 2009-2010; Coord: Patrick Boisseau CEA (France). IMT role; partner; IMT contact: Prof. Dan Dascalu (dan.dascalu@imt.ro);

► Hazard characterization and human and environment impact assessment of specific nanomaterials and associated products and exploration of new solutions for their sustainable use, re-use, recycling and final treatment and/or disposal – NANOSUSTAIN, NMP-2009-1.3-1; ENV.2009.3.1.3.2, Project coordinator: Dr. Rudolf Reuther, NordMiljö AB, IMT role: Partner; IMT contact Dr. Irina Kleps (irina.kleps@imt.ro).



EU projects related to FP 7

► Nanoelectronics for Safe, Fuel Efficient and Environment Friendly Automotive Solution – SE2A; ENIAC (nanoelectronics) 2008-20111, Coordinator: NXP Semiconductor Netherlands BV, The Netherlands. IMT role; partner; IMT contact: Dr.Alexandru Muller (alexandru.muller@imt.ro).

► MERCURE, <u>ENIAC</u> (nanoelectronics), Coordinator: Thales TRT, France; contact person: Dr.Alexandru Muller (<u>alexandru.muller@imt.ro</u>); accepted Oct 2009

Micro Nano Technology Use by SME's- MINATUSE, <u>EUREKA</u>, coord: Christophe Bruynseraede, IMEC, Belgium, 2005-2010, IMT role Partner; IMT Contact: Eng.Ionica Miresteanu, (<u>ionica.miresteanu@imt.ro</u>)

► Novel Gain Materials and Devices Based on III-V-N Compounds; <u>COST</u> Action MP0805, Coordinator: Prof. N. Balkan, University of Essex, UK. IMT role; partner; contact person: Dr.Alexandru Muller (<u>alexandru.muller@imt.ro</u>)



Development of competences of educational staff by integrating operational tasks into measures of vocational training and further education" ComEd, - Leonardo da Vinci - Life Long Learning (2008-2010) Coordinator BWAW Thüringen gGmbH, Germany, Contract Number : DE/08/LLP-LdV/TO/147174- (2008-2010) IMT role Partner; IMT Contact: Dr. Raluca Muller (raluca.muller@imt.ro)

ERA-NET projects

A "system-in-a-microfluidic package" approach for focused diagnostic DNA microchips (DNASIP) Coordinator: Université Catholique de Louvain, Belgium, Prof. Denis Flandre, role of IMT – partner, contact person: Phys. Monica Simion (monica.simion@imt.ro).

"Nanostructural carbonaceous films for cold emitters" (NANOCAFE), Coordinator: Industrial Institute of Electronics, Poland, Dr. Elżbieta Czerwosz, role of IMT – partner, contact: Phys. Florea Craciunoiu (florea.craciunoiu@imt.ro).



International partnership

- Apart of cooperation with dozens of organizations from Europe in EU projects IMT- Bucharest is involved in a great number of bilateral European projects (especially with Italy, France, Belgium),
- **Outside Europe**, **IMT- Bucharest** has also cooperation with organizations from:
 - Japan
 - Korea
 - Singapore;
 - South Africa.



Education

New Master (M. Sc. Courses) at the Faculty for Electronics, Communications and Information Technology, University "Politehnica" of Bucharest starting October 2009 and held in IMT (with access to experimental facilities).

• Microsystems:

- Intelligent sensors and microsystems;
- Microphysical characterization of structures;
- Micro- and Nanoelectronics:
 - Advanced Technological Processes
- Electronic Technology for Medical Applications:
 - Micro- and Nanotechnologies for Medical Applications



Postdoc program: A Postdoc program in the areas of RF MEMS and MOEMS financed by FP7 MIMOMEMS project was launched in 2009 in IMT. Three postdocs were employed in IMT up to now.

Postdoc program Human Resource Development by Postdoctoral Research on Micro and Nanotechnologies

> Other educational actions within different projects:

• FP 6: ASSEMIC - Marie Curie Training Network (2004-2007), Contract No. MRTN-CT-2003-504826, supervising the activity of PhD students and post doc.

• 2 Leonardo da Vinci - Life Long Learning projects, where IMT was partner:

- "Microteaching Project" (2004-2007), coordinated by RWTH Aachen University

- "Development of competences of educational staff by integrating operational tasks into measures of vocational training and further education" ComEd, (2008-2010) coordinated by BWAW Thüringen gGmbH, Germany

• Short courses regarding microtechnologies were developed and presented to SMEs.



View from the **new clean room**



Reactive Ion Etching (RIE), SENTECH equipment

Working gases: CF4, CHF3, SF6, O2, Ar RF power could be varied between 0 si 600 W, pressure in reactor between 1 – 100 Pa, and wafers of 3 and 4 inch

Conventional and nonconventional technological processes:

• Etching: Si, SiC, SiO2, polySi, Si3N4, TiO2, SU8, PDMS, PMMA

 Physical-chemical reactions at room temperature for the modification of the surfaces (contact angle, superficial polymerization, hydrophilic and/or hydrophobic surfaces).

• Plasma RF treatments for improving the substrate adherence.





Vacuum coating system

Processes:

- DC sputtering
- e-beam

Chamber size: 500mm x 500mm

Coating materials: AI, Ni, Cr, Au, Pt, Ti, W, etc

Up to 6 coatings in a single vacuum process (4 e-beam, and 2 sputtering)





Pattern generator for mask manufacturing DWL 66fs Laser Lithography System is produced by Heidelberg Instruments Mikrotechnik GmbH.

APPLICATIONS:

-masks manufacturing **for all semiconductor applications** (minimum pattern : 1 μm

-direct writing (wafers, different substrate types) using various photosensitive coatings (positive and negative resists, SU8, photosensitive polyimide) for all semiconductor applications

-**3D structuring** in thick photosensitive materials



Dip Pen Nanolithography system

This scanning probe lithography technique allows pattering in nanometre range and is a direct writing method that can use molecular and biomolecular "inks" on a variety of substrates



Enables deposition of tracks of various materials (polymers, sol-gel precursors, nanopowder, complex molecules, quantum dots) with a thickness down to **30 nm**.







Equipments acquired in the **MIMOMEMS** project

Vector Network Analyzer (VNA) up to 110 GHz and on wafer measurement facilities in order to upgrade the 0.8-65 GHz existing on wafer characterization system

Frequency synthesiser up to 65GHz

Au plating facility for semiconductor wafers

White light interferometer- optical profiling system for research applications

Near field scanning optical microscope (SNOM)







Near field scanning optical microscope (SNOM) – purchased in the frame of FP7 Project MIMOMEMS







Confocal image of round structure 30X30 μm scanning area

SNOM image in contact mode of an Au array of lines patterned using EBL – 2X2 μm scanning area

Operating Modes:

Near-field microscopy: transmission, reflection, collection, fluorescence *Confocal microscopy:* transmission, reflection, fluorescence, can be upgraded with a Raman spectrometer *Atomic Force Microscopy* contact and AC-

Mode

Applications:

- Imaging the optical properties of a sample with resolution below the diffraction limit with applications in nanotechnology, nanophotonics , nanooptics and plasmonics

- Life sciences
- Materials research
- Single molecule detection .

Field Emission Gun Scanning Electron Microscope (FEG-SEM) *Nova NanoSEM 630* FEI Company,

-ultra high resolution in the nanoscale range, for a variety of applications that involve sample characterization, analysis for S/TEM sample preparation

Research

- Materials Qualification
- Surface morphology inspection
- Nanometrology
- -Device Characterization

Main current cooperation

- INFN Rome
- FORTH Heraklion
- Univ. Salerno
- Univ. Kyoto





CNT and graphene



White Light Interferometer (WLI) - Photomap 3D Standard 2006 (FOGALE NANOTECH);







3D image of a 60GHz monolithically integrated receiver micromachined on GaAs

Detail of a silicon micromachined filter



NANOSCALE LAB

High aspect ratio (12:1) structures in PMMA





Mix-and-match lithography for biomedical applications: optical lithography (left), combined with EBL (right) Diffractive Optical Element (DOE) for photonics applications



Photonic cristals in PMMA on silicon for near IR applications







Mix- match litography for 300 nm fingers used for SAW devices (Cooperation IMT Bucharest- IESL FORTH)



NANOSCALE LAB



Structure obtained using conventional litogrtaphy and EBID for 4 probes measurements of electrical properties of a polymer nanowire (Coopertaion IMT Bucharest – UCL)





- Polymer nanowire electrically contacted using EBID (Coopertaion IMT Bucharest – UCL)
- Nanolithography with sub 20 nm resolution;
- Three-dimensional nanostructures;
- CNT based interconnections for next-generation integrated circuits
- CNT based nanodevices

- **Contact Person: Phys. Adrain Dinescu**
- SAW devices with nanometer interdigitated electrodes;
- Optical devices, holograms, micro lenses, gratings
- Development of Nanodevices using E-beam induced deposition and etching
- Development of circuits for communications based on photonic crystals



Reliability Tests

- Semiconductor Characterization System (DC) with WaferProbing Station *4200SCS/C/-*
- various modules- (Keithley Instruments, USA)
- Mobile Thermal Airstream System ThermoStream TP04300A-8C3-11 (Temptronic, USA)
- Damp heat Climatic chamber (Angelantoni, Italy)
- Electrodynamic vibration system with thermal and electrical tests
- TV 55240/LS (TIRA, Germany)
- Thermal shock chamber TSE-11-A (Espec Europe, Germany)
- Universal Ovens with electrical testing UFB 400 (Memmert, Germany)
- Highly Accelerated Stress Test Chamber temperature, humidity, pressure, polarization - *EHS-211M* (Espec Europe, Germany)

-Free Fall Shock Machine - 0707-20 (MRAD, USA)







Modelling and Simulation Tools

- COVENTOR 2009 (modules: Architect; FlowMM; MemHenry; MemPackage; Designer; Analyzer Std. ; MemOptics)
- MATLAB 7: Optimization Toolbox; Extended Symbolic Math Toolbox; Partial Differential Equation Toolbox; Genetic Algorithm and Direct Search Toolbox; Statistics Toolbox; Neural Network Toolbox; Curve Fitting Toolbox; Spline Toolbox; Signal Processing Toolbox; Image Processing Toolbox; Simulink
- **ANSYS Multiphysics 11.0-** Structural, thermal, acoustic, electromagnetic and coupled field analyses, CFD
- **COMSOL Multiphysics 3.3** and **3.4** (enabling parallel computation)
- **Workstation** with 4 quad-core Intel Xeon MP 2.93 GHz processors, 64 GByte RAM and 584 GByte HDD + 876 GByte external storage

Computer aided design and simulation for passive and active micro-photonic components using Opti-FDTD6.0 and OptiBP
Microwave electromagnetic simulations using IE3D and Fidelity from ZELAND software



IMT-MINAFAB full info - www.imt.ro/MINAFAB/

IMT-Bucharest - Brochure for scientific-technological services - <u>www.imt.ro/brosura_imt_bucuresti_2009.pdf</u>

Quick list of capabilities and tools http://www.imt.ro/MINAFAB/description.htm

Thank you for your attention!